

ABSTRACT**COMPOSITION FOR METAL PLATING COMPRISING SUPPRESSING AGENT FOR VOID FREE
SUBMICRON FEATURE FILLING**

A composition comprising a source of metal ions and at least one suppressing agent obtainable by reacting a) an amine compound comprising active amino functional groups with b) a mixture of ethylene oxide and at least one compound selected from C3 and C4 alkylene oxides, said suppressing agent having a molecular weight M_w of 6000 g/mol or more.

Figure 6b